

## **AN-1805 LMV243 Single-Channel, Quad-Band GSM Power Controller Evaluation Board**

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### **1 General Description**

This board can be used to evaluate the Texas Instruments LMV243 Single-Channel, Quad-Band GSM Power Controller. The device is intended for use within an RF transmit power control loop in GSM mobile phones and supports GaAs HBT and bipolar RF single supply power amplifiers (PA's). The key value is its immunity to changes in the PA gain control function. It contains a 50 dB logarithmic amplifier detector and interfaces directly with the directional coupler. The operating frequency range of the device is from 450 MHz to 2 GHz .

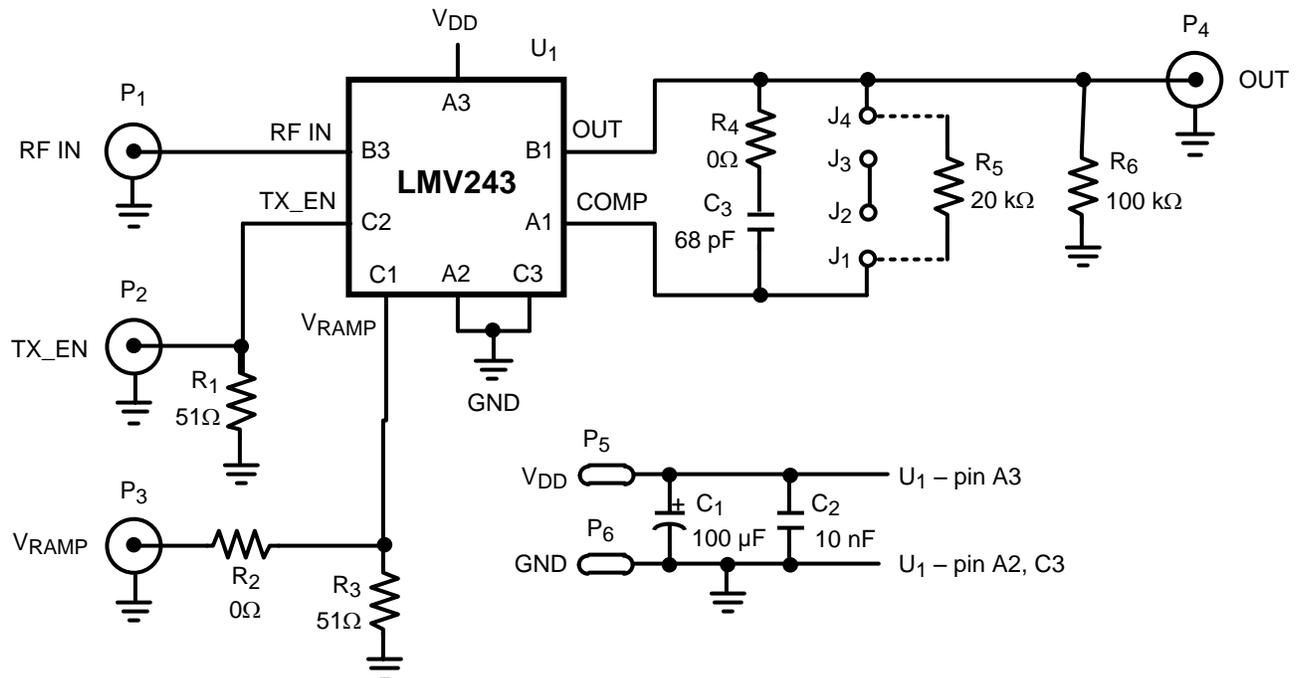
### **2 Basic Operation**

The LMV243 RF power controller provides an accurate temperature compensated DC output voltage (with a negative slope) that relates linearly to the applied RF input power in dBm. To evaluate the LMV243 in a simple straight forward way, the control loop is formed by the LMV243 and resistor  $R_5$  instead of LMV243, PA, and a directional coupler. In an actual closed loop TX control system, including a PA, resistor  $R_5$  should be removed. In an open loop measurement configuration the output voltage ramps down with increasing input power from a maximum voltage defined by  $V_{RAMP}$ . This maximum output voltage equals  $V_{OUT} = V_{RAMP} * R_5 / R_{RAMP}$ , where  $1/R_{RAMP}$  is the transconductance defined in the datasheet.

The single supply voltage ranges from 2.7V to 3.3V and can be applied through connectors  $P_5$  and  $P_6$ . The input interface consists of the RF input ( $P_1$ ), a ramp voltage applied through  $P_3$  and a digital input TX\_EN ( $P_2$ ) to perform the function "Shutdown/Transmit Enable." The device will be active in the case TX\_EN = HI, otherwise, the device is in a low power consumption shutdown mode. During shutdown the output will be in high impedance mode (tristate). A single external RC combination is used to provide stable operations that accommodates individual PA characteristics. This is done with resistor  $R_4$  and capacitor  $C_3$ .

### 3 Schematic

The schematic of the evaluation board is shown in [Figure 1](#).



**Figure 1. Schematic of the Evaluation Board**

### 4 Bill of Materials

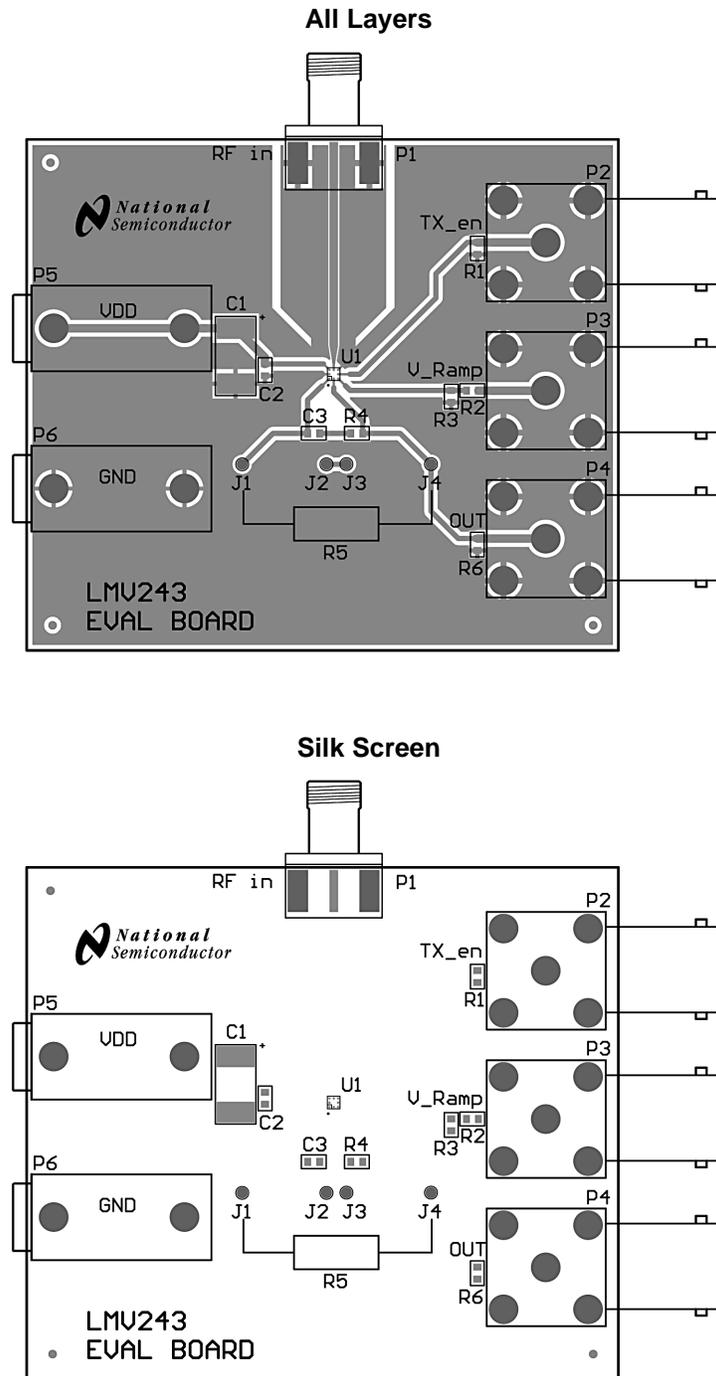
The Bill of Material (BOM) of the evaluation board is listed in [Table 1](#).

**Table 1. Bill of Materials of the Evaluation Board**

Designator	Description	Comment
C1	Case_D Capacitor	100 μF
C2	0603 Capacitor	10 nF
C3	0603 Capacitor	68 pF
P1	Connector	SMA
P2, P3, P4	Connector	BNC
P5, P6	Connector	Banana
R1, R3	0603 Resistor	51Ω
R2, R4	0603 Resistor	0Ω
R5	Axial Resistor	20 kΩ
R6	0603 Resistor	100 kΩ
U1	DSBGA	LMV243

## 5 Layout

The layout of the evaluation board is shown in [Figure 2](#).

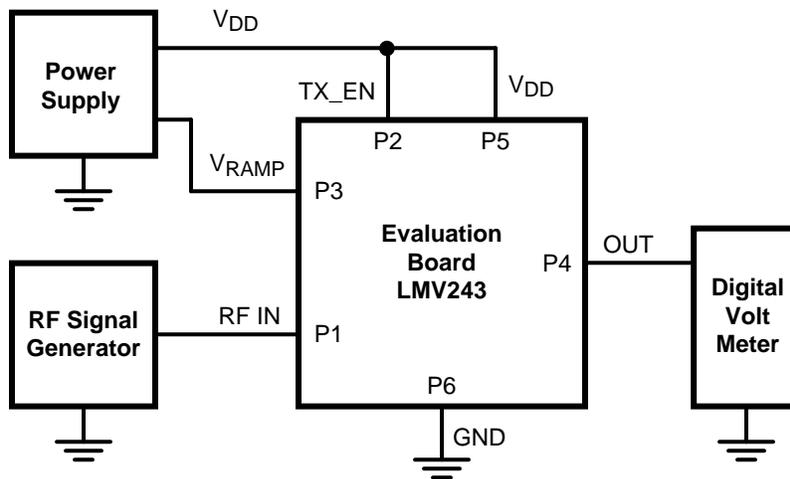


**Figure 2. Layout of the Evaluation Board**

## 6 Measurement Procedure

The performance of the LMV243 can be measured with the setup shown in [Figure 3](#).

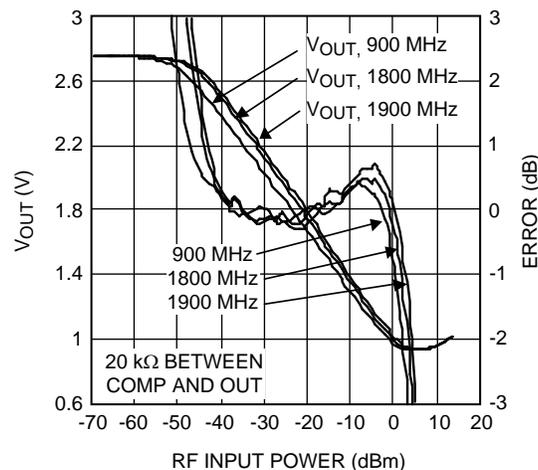
In this measurement example a supply voltage of 2.8V is applied by the power supply. The LMV243 is set in active mode by connecting TX\_EN (P<sub>2</sub>) to V<sub>DD</sub>, which is 2.8V. V<sub>RAMP</sub> is set to 1.4V. An RF signal is applied by the RF generator to connector P<sub>1</sub>. The RF power is swept from -70 dBm to +16 dBm. The resulting output voltage is measured with a multimeter connected to P<sub>4</sub>.



**Figure 3. Measurement Setup**

## 7 Measurement Results

[Figure 4](#) shows the output voltage and the log conformance error versus the applied RF power. The RF power is swept for three different frequencies.



**Figure 4. Frequency Response**

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